Storage Conditions of
Printed Circuit Boards / Multilayer

1.	The materials used for manufacturing multilayer are " hydroscopic", i.e. they absorb moisture during storage (drying is reversible process).
2.	The absorbed moisture vaporizes during the "Reflow process" in a very short time, which can lead to de-lamination.
3.	The conditions and duration of storage have an influence on the absorption of moisture.
4.	Preferred conditions of storage: **Temperature: 20 +/- 5 ° C, Relative humidity: 45 +/- 15%**
5.	Special storage Conditions for PCBs processed with Chemical Tin surface finish Storage Conditions and Product Handling at Assembly - The product should be stored in the sealed airtight packages until assembly occurs. - When handling the product, gloves should be worn and contact with the metalized /plated areas must be avoided. - Once the vacuum package is opened, the following conditions shall be maintained: a) Relative Humidity < 50%, Temperature 20 – 25 °C, b) Assembly must occur within one week c) PCBs shall not be exposed to corrosive gas or liquid environment d) PCBs shall not be exposed to direct sun light e) Fingerprints must be avoided - Opened packages may be kept for a maximum of one week if they are stored slip-sheeted and stacked, (i.e. not in racks)
6.	Corresponding storage times for finish surface to meet the soldering requirements: - HAL (Hot Air Leveling) - 6 months - Nickel / Gold (Immersion Gold) - 6 months - Chemical Tin - 6 months - Bond Gold - 6 months
7.	The product should be stored in the sealed airtight packages until assembly occurs.
8.	Under the above stated conditions of storage multilayer can be soldered within 12 months.
9.	The User immediately, but no later than 10 days upon receipt of the goods at the place of destination, performs an entry PCB control according to IPC-A- 600, notifies (in writing) the defects that have been detected and exactly describes the type of the defects.